

C2225X224KBRACTU

Aliases (C2225X224KBRAC7800)

SMD Comm X7R HV Flex, Ceramic, 0.22 uF, 10%, 630 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 2225, 3.2 mm



General Information	
Series	SMD Comm X7R HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	430 mg
Shelf Life	78 Weeks
MSL	1

0.22 uF

1 kHz 1.0Vrms

454.5 MOhms

Dimensions	
Chip Size	2225
L	5.9mm +/-0.75mm
W	6.4mm +/-0.4mm
Т	1.6mm +/-0.20mm
S	3.2mm MIN
В	0.7mm +/-0.35mm

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Packaging Specifications	

W	6.4mm +/-0.4mm	Tolerance	10%
T	1.6mm +/-0.20mm	Voltage DC	630 VDC
S	3.2mm MIN	Dielectric Withstanding Voltage	945 VDC
В	0.7mm +/-0.35mm	Temperature Range	-55/+125°C
		Temp. Coefficient	X7R
Packaging Specifications		Capacitance Change with	15%, 1kHz 1.0Vrms
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Packaging Specifications Packaging	T&R, 180mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC	15%, 1kHz 1.0Vrms 2.5% 1 kHz 1.0Vrms

Specifications

Measurement Condition

Insulation Resistance

Capacitance

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